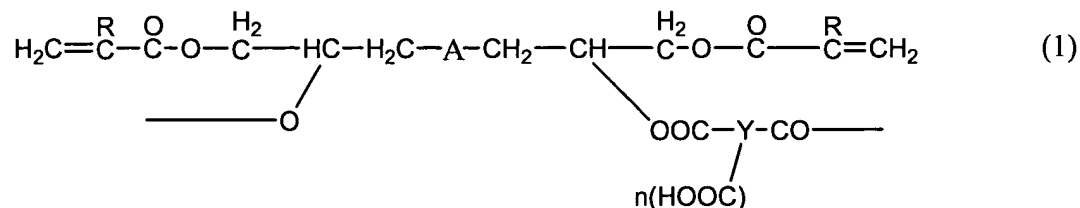


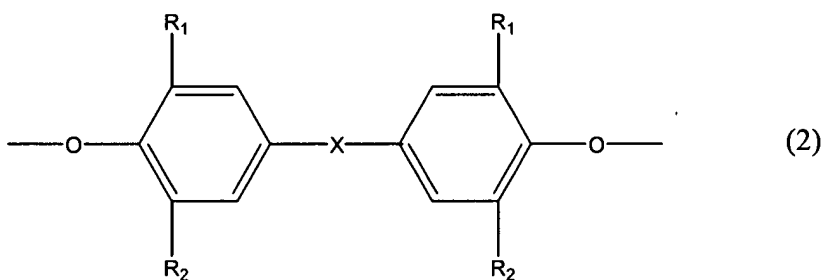
IN THE CLAIMS:

1. (currently amended) A photo- or heat-curable resin composition comprising,

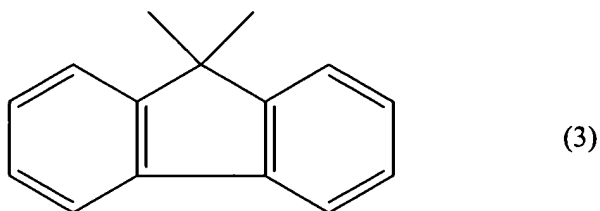
a) 100 parts by weight of (A) unsaturated compound having a structural unit represented by the following general formula (1)



(wherein R is hydrogen or methyl group, A is a group represented by the formula (2), Y is the residue of a polycarboxylic acid or its acid anhydride, and n is integer of 0-3)



(wherein R<sub>1</sub> and R<sub>2</sub> are hydrogen, an alkyl group with 1-5 carbon atoms, or a halogen and X is -CO-, ~~-SO-~~, ~~-SO<sub>2</sub>-~~, -C(CF<sub>3</sub>)<sub>2</sub>-, -Si(CH<sub>3</sub>)<sub>2</sub>-, -CH<sub>2</sub>-, -C(CH<sub>3</sub>)<sub>2</sub>-, -O-, -S-, group represented by the formula (3) or single bond),



b) 10-100 parts by weight of (B) which is at least one acrylate selected from (meth)acrylates or oligomers thereof, wherein said at least one acrylate is modified with ethylene oxide or propylene oxide, and wherein said at least one acrylate is selected from the group consisting of:

hydroxyethyl (meth)acrylate, hydroxypropyl (meth)acrylate, 2-hydroxyethylhexyl (meth)acrylate, polyethylene glycol mono(meth)acrylate, polypropylene glycol mono(meth)acrylate, butanediol mono(meth)acrylate, chlorohydroxypropyl (meth)acrylate, allyl (meth)acrylate, butoxyethyl (meth)acrylate, triethylene glycol butyl ether (meth)acrylate, t-butylaminoethyl (meth)acrylate, caprolactone (meth)acrylate, butyl (meth)acrylate, hexyl (meth)acrylate, cyanoethyl (meth)acrylate, dimethylaminoethyl (meth)acrylate, diethylamino (meth)acrylate, ethoxyethyl (meth)acrylate, ethylhexyl (meth)acrylate, isodecyl (meth)acrylate, isooctyl (meth)acrylate, lauryl (meth)acrylate, octyl (meth)acrylate, stearyl (meth)acrylate, succinic acid (meth)acrylate, methacryloyloxypropyl-trimethoxysilane, methoxyethyl (meth)acrylate, cyclodecatrienyl (meth)acrylate, glycerol (meth)acrylate, glycidyl (meth)acrylate, isocyanatoethyl (meth)acrylate, heptadecafluorooctyl (meth)acrylate, octafluoropentyl (meth)acrylate, tetrafluoropropyl (meth)acrylate, trifluoroethyl (meth)acrylate, dibromopropyl

(meth)acrylate, cyclohexyl (meth)acrylate, dicyclopentanyl  
(meth)acrylate, dicyclopentenyl (meth)acrylate, isobornyl  
(meth)acrylate, tetrahydrofurfuryl (meth)acrylate,  
morpholino (meth)acrylate, phenoxyethyl (meth)acrylate,  
phenoxyhydroxypropyl (meth)acrylate, polypropylene glycol  
nonylphenyl ether (meth)acrylate, phenyl (meth)acrylate,  
phthalic acid (meth)acrylate, benzyl (meth)acrylate,  
phenoxyated phosphoric acid (meth)acrylate, phosphoric acid  
(meth)acrylate, butoxyated phosphoric acid (meth)acrylate,  
octoxyated phosphoric acid (meth)acrylate, sodium sulfonate  
(meth)acrylate, ethylene glycol di(meth)acrylate, diethylene  
glycol di(meth)acrylate, hexanediol di(meth)acrylate,  
di(meth)acrylates of long-chain aliphatic diols, neopentyl  
glycol di(meth)acrylate, hydroxypivalic acid neopentyl  
glycol di(meth)acrylate, stearic acid-modified  
pentaerythritol di(meth)acrylate, propylene glycol  
di(meth)acrylate, glycerol di(meth)acrylate, triethylene  
glycol di(meth)acrylate, tetraethylene glycol  
di(meth)acrylate, triethylene glycol divinyl ether,  
tetramethylene glycol di(meth)acrylate, butylene glycol  
di(meth)acrylate, dicyclopentanyl di(meth)acrylate,  
polyethylene glycol di(meth)acrylate, polypropylene glycol  
di(meth)acrylate, triglycerol di(meth)acrylate, neopentyl  
glycol-modified trimethylolpropane di(meth)acrylate,  
allylated cyclohexyl di(meth)acrylate, methoxylated

B  
cyclohexyl di(meth)acrylate, acrylic group-substituted  
isocyanurate, bis(acryloyloxyneopentyl) adipate, bisphenol A  
di(meth)acrylate, ~~tetrabromobisphenol A di(meth)acrylate,~~  
bisphenol S di(meth)acrylate, butanediol di(meth)acrylate,  
phthalic acid di(meth)acrylate, phosphoric acid  
di(meth)acrylate, zinc di(meth)acrylate, trimethylolpropane  
tri(meth)acrylate, trimethylolethane tri(meth)acrylate,  
glycerol tri(meth)acrylate, pentaerythritol  
tri(meth)acrylate, alkyl-modified dipentaerythritol  
tri(meth)acrylate, phosphoric acid tri(meth)acrylate,  
tris((meth)acryloyloxyethyl) isocyanurate, pentaerythritol  
tetra(meth)acrylate, dipentaerythritol tetra(meth)acrylate,  
ditrimethylol-propane tetraacrylate, alkyl-modified  
dipentaerythritol tetra(meth)acrylate, dipentaerythritol  
penta(meth)acrylate, dipentaerythritol hexa(meth)acrylate,  
alkyl-modified dipentaerythritol penta(meth)acrylate,  
urethane tri(meth)acrylate, ester tri(meth)acrylate,  
urethane hexa(meth)acrylate, and ester hexa(meth)acrylate;  
c) 0-50 parts by weight of (C) compound containing epoxy group  
and  
d) 0-10 parts by weight of (D) photopolymerization initiator or  
sensitizer.

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2. (original) A photo- or heat-curable resin composition as  
described in claim 1 wherein at least a part of the unsaturated

compound (A) is an unsaturated compound having the fluorene skeleton represented by the formula (3) in its structural unit.

3. (original) A photo- or heat-curable resin composition as described in claim 1 wherein at least one kind of other unsaturated compound (E) selected from other monomers and oligomers is incorporated at a rate of 100 parts or less per 100 parts by weight of the component A in addition to the components A, B, C and D.

4. (withdrawn) A printed wiring board wherein a resin insulation layer is formed by the cured product of a photo- or heat-curable resin composition as described in claim 1.

5. (withdrawn) A cured resin formed by curing a photo- or heat-curable resin composition as described in claim 1.

6. (previously presented) A photo- or heat-curable resin composition as described in claim 1, wherein the at least one acrylate is selected from the group consisting of trimethylolpropane tri(meth)acrylate, trimethylolethane tri(meth)acrylate, glycerol tri(meth)acrylate, and pentaerythritol tri(meth)acrylate or oligomers thereof.